

Advanced Power MOSFET

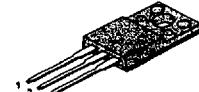
SSS5N90A

FEATURES

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 25 μ A (Max.) @ V_{DS} = 900V
- Low $R_{DS(ON)}$: 2.300 Ω (Typ.)

$BV_{DSS} = 900 \text{ V}$
 $R_{DS(on)} = 2.9 \Omega$
 $I_D = 3 \text{ A}$

TO-220F



1.Gate 2. Drain 3. Source

Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	900	V
I_D	Continuous Drain Current ($T_c=25^\circ\text{C}$)	3	A
	Continuous Drain Current ($T_c=100^\circ\text{C}$)	1.9	
I_{DM}	Drain Current-Pulsed ①	20	A
V_{GS}	Gate-to-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy ②	524	mJ
I_{AR}	Avalanche Current ①	3	A
E_{AR}	Repetitive Avalanche Energy ①	4.5	mJ
dv/dt	Peak Diode Recovery dv/dt ③	1.5	V/ns
P_D	Total Power Dissipation ($T_c=25^\circ\text{C}$)	45	W
	Linear Derating Factor	0.36	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
	Maximum Lead Temp. for Soldering Purposes, 1/8 " from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta_{JC}}$	Junction-to-Case	--	2.78	$^\circ\text{C}/\text{W}$
$R_{\theta_{JA}}$	Junction-to-Ambient	--	62.5	



SSS5N90A

N-CHANNEL
POWER MOSFET

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	900	--	--	V	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$
$\Delta \text{BV}/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	1.14	--	V/°C	$I_D=250\mu\text{A}$ See Fig 7
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	2.0	--	3.5	V	$V_{\text{DS}}=5\text{V}, I_D=250\mu\text{A}$
I_{GSS}	Gate-Source Leakage, Forward	--	--	100	nA	$V_{\text{GS}}=30\text{V}$
	Gate-Source Leakage, Reverse	--	--	-100		$V_{\text{GS}}=-30\text{V}$
I_{DSS}	Drain-to-Source Leakage Current	--	--	25	μA	$V_{\text{DS}}=900\text{V}$
		--	--	250		$V_{\text{DS}}=720\text{V}, T_C=125^\circ\text{C}$
$R_{\text{DS(on)}}$	Static Drain-Source On-State Resistance	--	--	2.9	Ω	$V_{\text{GS}}=10\text{V}, I_D=1.5\text{A}$ ④*
g_{fs}	Forward Transconductance	--	3.06	--	℧	$V_{\text{DS}}=50\text{V}, I_D=1.5\text{A}$ ④
C_{iss}	Input Capacitance	--	1110	1440	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}, f=1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	--	105	125		
C_{rss}	Reverse Transfer Capacitance	--	43	50		
$t_{\text{d(on)}}$	Turn-On Delay Time	--	21	50	ns	$V_{\text{DD}}=450\text{V}, I_D=5\text{A},$ $R_G=13.6\Omega$ See Fig 13 ④ ⑤
t_r	Rise Time	--	39	90		
$t_{\text{d(off)}}$	Turn-Off Delay Time	--	94	200		
t_f	Fall Time	--	32	75		
Q_g	Total Gate Charge	--	54	70	nC	$V_{\text{DS}}=720\text{V}, V_{\text{GS}}=10\text{V},$ $I_D=5\text{A}$ See Fig 6 & Fig 12 ④ ⑤
Q_{gs}	Gate-Source Charge	--	9.0	--		
Q_{gd}	Gate-Drain("Miller") Charge	--	25.0	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_s	Continuous Source Current	--	--	3	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current ①	--	--	20	A	
V_{SD}	Diode Forward Voltage ④	--	--	1.4	V	$T_J=25^\circ\text{C}, I_s=3\text{A}, V_{\text{GS}}=0\text{V}$
t_r	Reverse Recovery Time	--	540	--	ns	$T_J=25^\circ\text{C}, I_F=5\text{A}$
Q_{rr}	Reverse Recovery Charge	--	5.62	--	μC	$dI_F/dt=100\text{A}/\mu\text{s}$ ④

Notes :

- Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- $L=110\text{mH}, I_{As}=3\text{A}, V_{DD}=50\text{V}, R_G=27\Omega$, Starting $T_J=25^\circ\text{C}$
- $I_{SD} \leq 5\text{A}, di/dt \leq 120\text{A}/\mu\text{s}, V_{DD} \leq \text{BV}_{\text{DSS}}$, Starting $T_J=25^\circ\text{C}$
- Pulse Test : Pulse Width = $250\mu\text{s}$, Duty Cycle $\leq 2\%$
- Essentially Independent of Operating Temperature

N-CHANNEL
POWER MOSFET

SSS5N90A

Fig 1. Output Characteristics

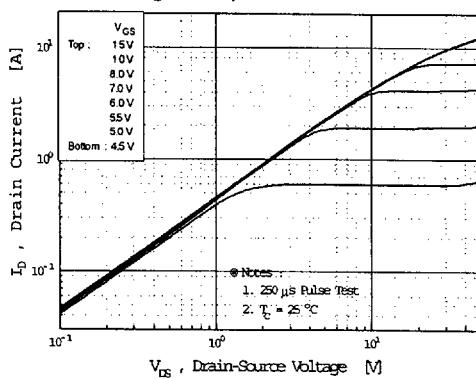


Fig 2. Transfer Characteristics

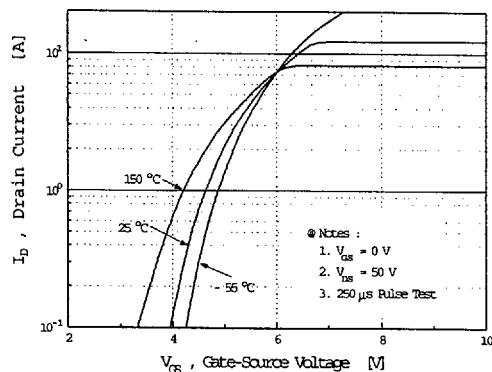


Fig 3. On-Resistance vs. Drain Current

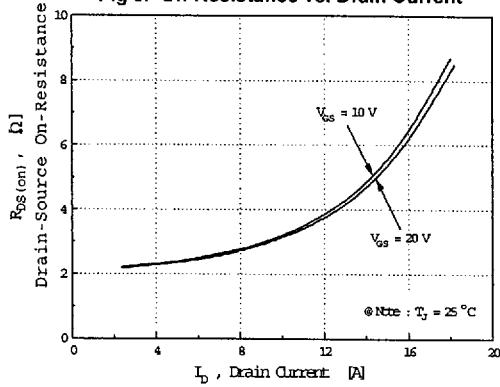


Fig 4. Source-Drain Diode Forward Voltage

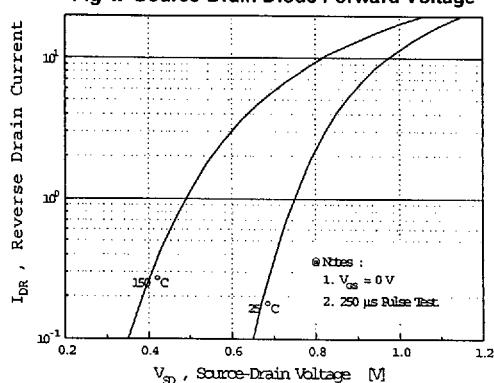


Fig 5. Capacitance vs. Drain-Source Voltage

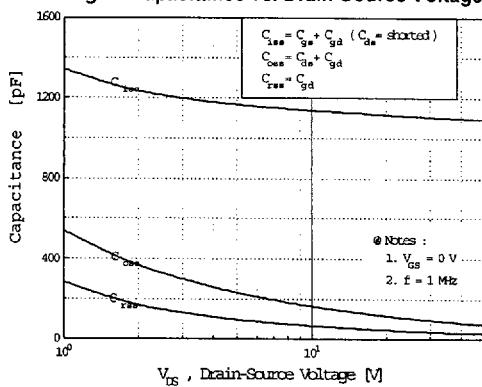
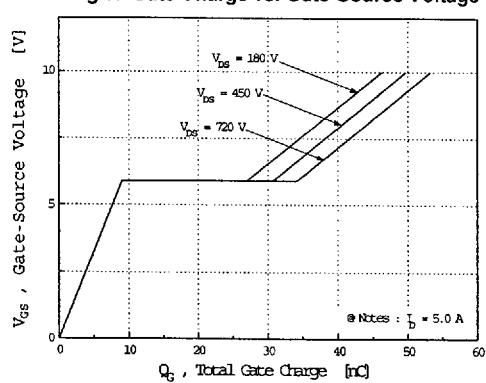
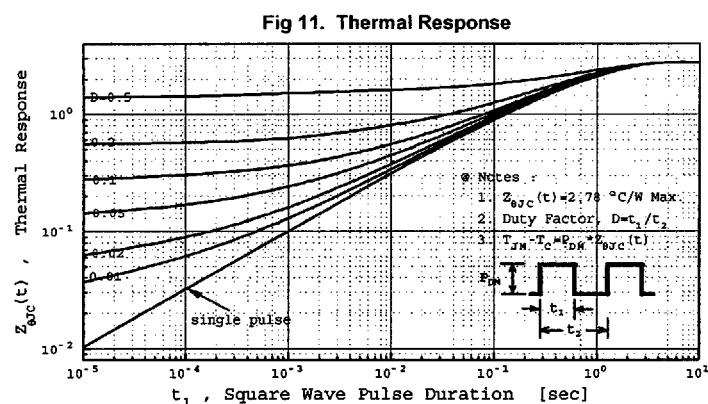
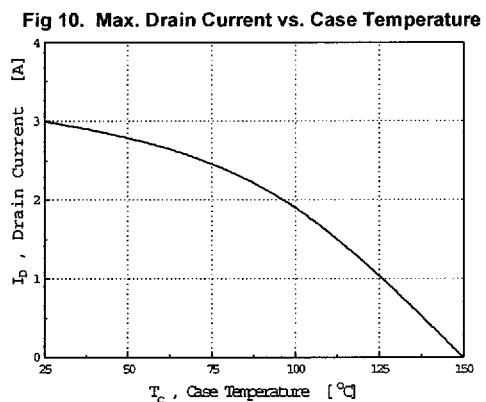
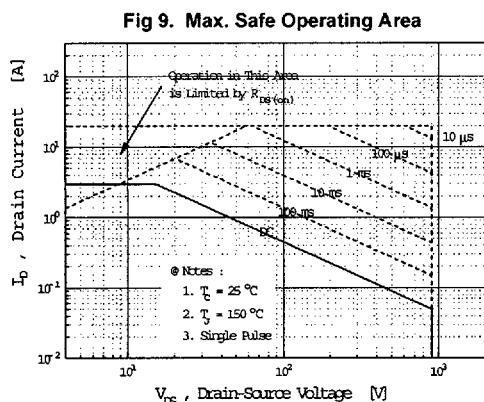
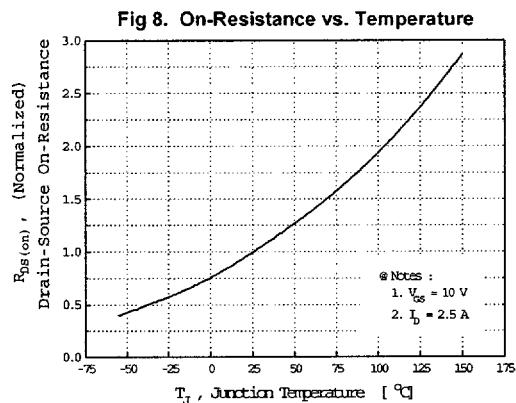
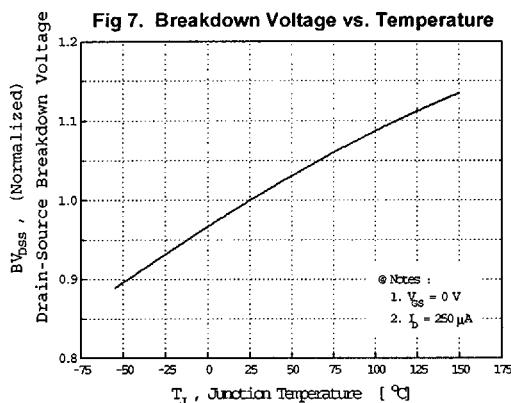


Fig 6. Gate Charge vs. Gate-Source Voltage



SSS5N90A

N-CHANNEL POWER MOSFET



N-CHANNEL
POWER MOSFET

SSS5N90A

Fig 12. Gate Charge Test Circuit & Waveform

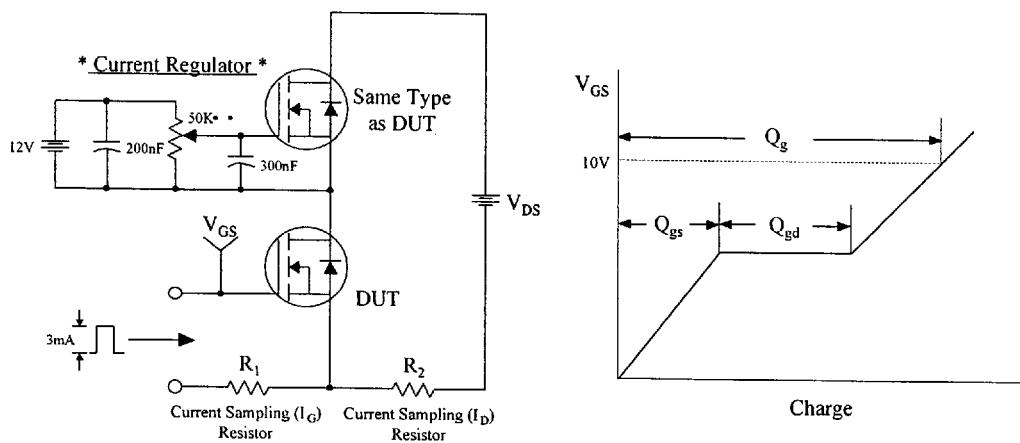


Fig 13. Resistive Switching Test Circuit & Waveforms

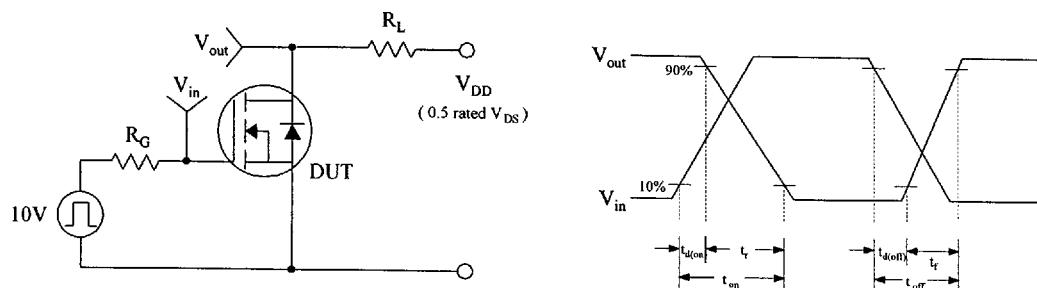
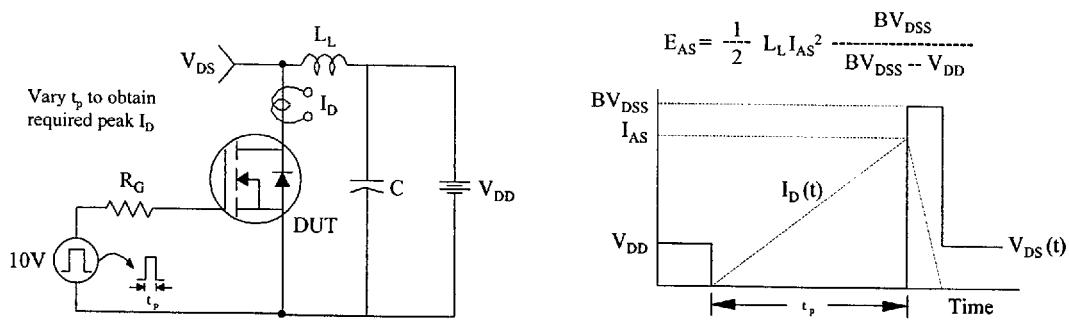
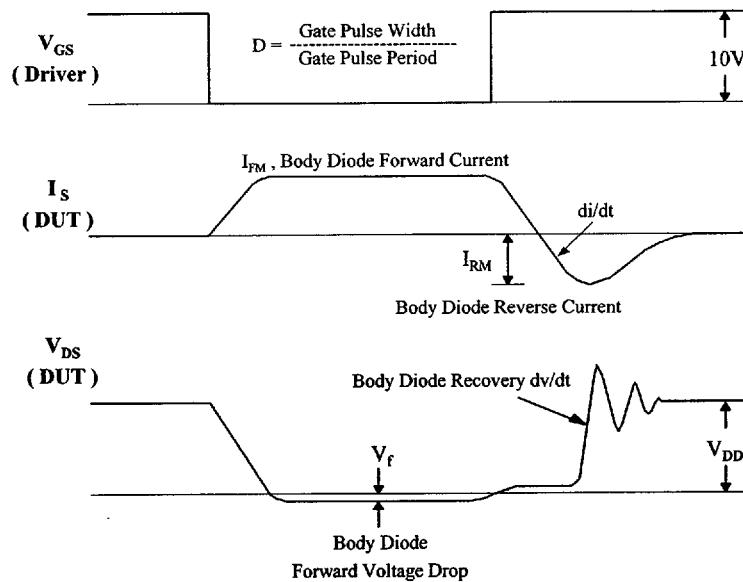
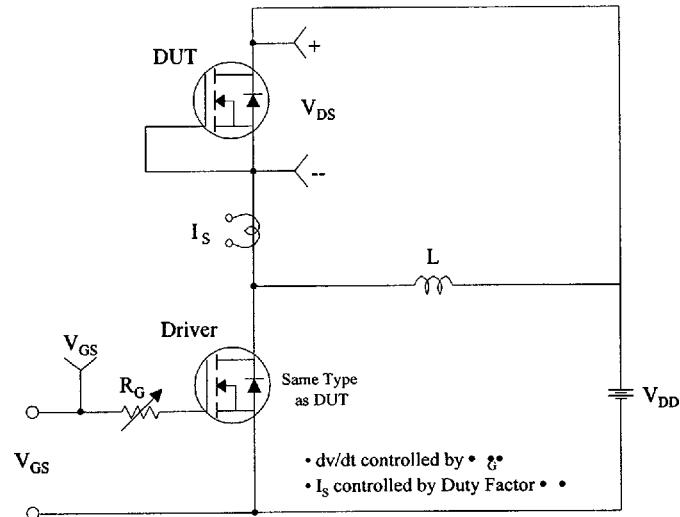


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



SSS5N90A

Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



SAMSUNG
ELECTRONICS